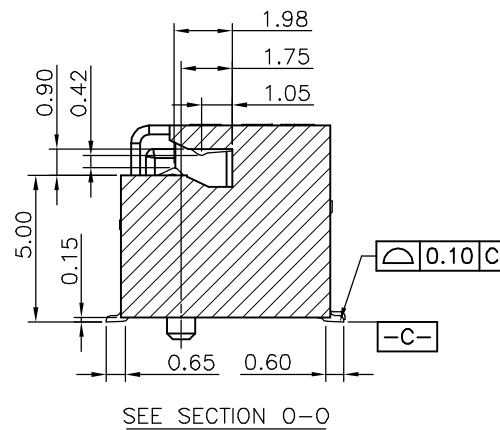
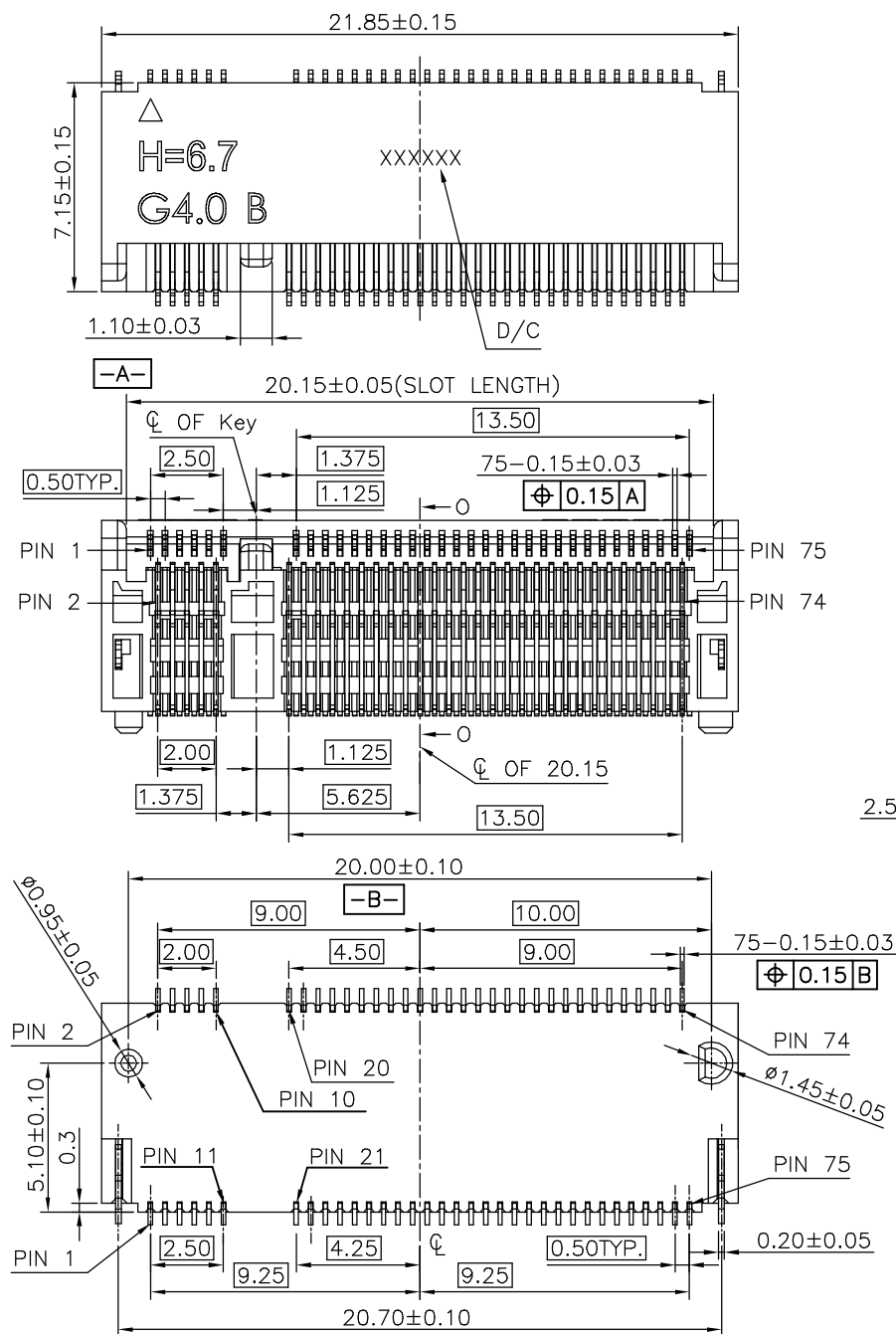




- Notes:
1. MATERIAL SPECIFICATION:
 - 1.1. HOUSING:LCP+40%GF,UL94V-0,COLOR:BLACK.
 - 1.2. CONTACT:COPPER ALLOY.
 - 1.3. PEG:STEEL.
 2. PLATING SPECIFICATION:
 - 2.1. CONTACT:50u" MIN.NICKEL UNDER PLATING
OVER ALL.PLATING ON SOLDER AREA:SEE TABLE
GOLD PLATING ON CONTACT AREA:SEE TABLE
 - 2.2. PEG:50u" MIN. NICKEL UNDER PLATING OVER ALL.
80u" MIN. MATTE TIN PLATING ON SOLDER AREA.
 3. HF COMPLIANT, RoHS COMPLIANT.
 4. DATE CODE: XX XX XX

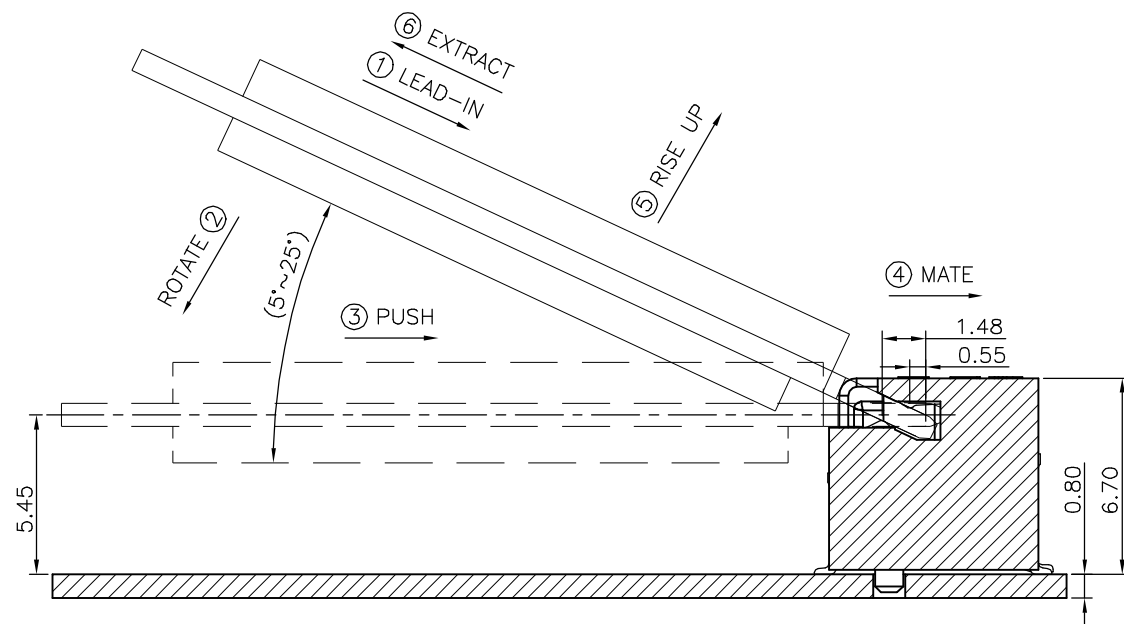
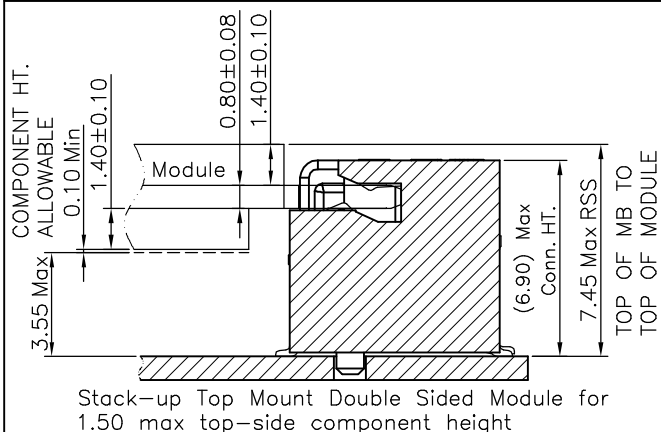
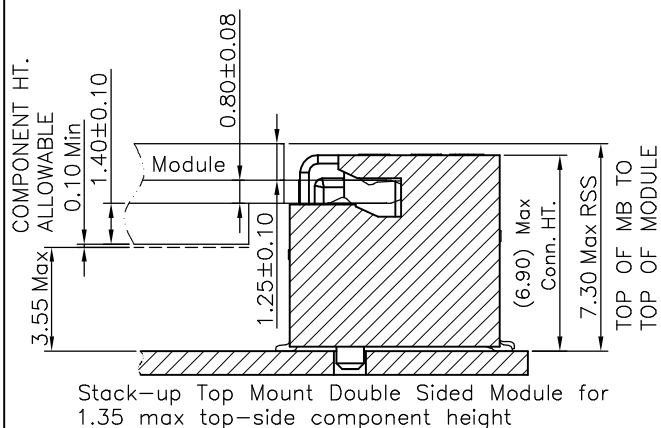
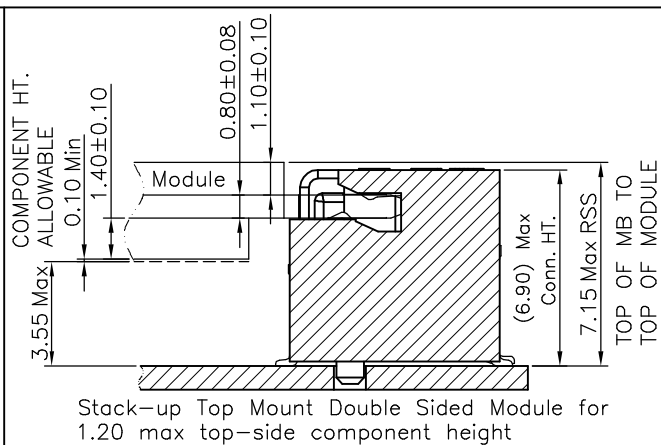
DAY
WEEK
YEAR
 5. MECHANICAL PERFORMANCE:
 - 5.1. DURABILITY: SEE TABLE
 6. ELECTRICAL PERFORMANCE:
 - 6.1. CURRENT: 0.5A PER PIN.
 - 6.2. LLCR: INITIAL 55mΩ MAX.;FINAL Δ LLCR=20mΩ MAX.
 7. IR REFLOW:
THE TEMPERATURE SHALL BE 260±5°C MAINTAINING 10±1 SECONDS.



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TOLERANCE:		DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NGFF M.2 B KEY 6.7H 0.5PH PCIe 4.0	
X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X.* ±2* X.X* ±0.5*				PART NO.	HYCW33B-05NGFF-670B
 UNIT: mm [inch]		CHECKED BY: 马跃	DATE : 2014-02-23	MOLD NO.	
		APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO:	HYC-2202281723
SCALE:1:1	SIZE: A4			SHEET NO.	1 OF 1

Assembly stack height schematic diagram



HOW TO MATE AND EXTRACT

MATE: ① → ④

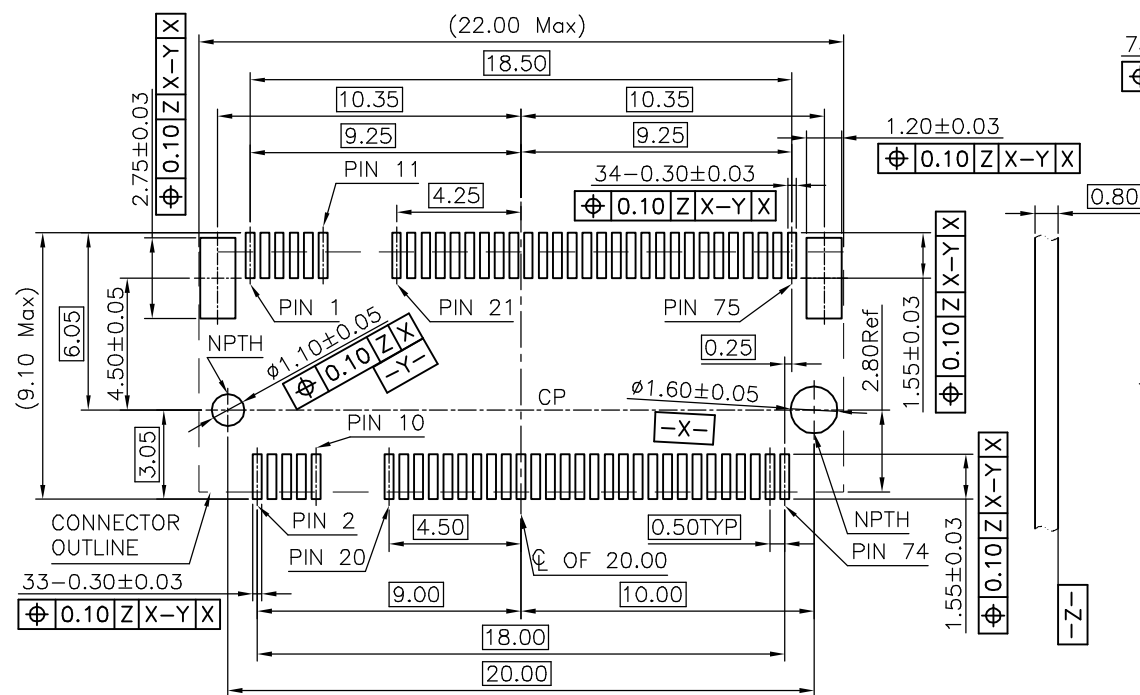
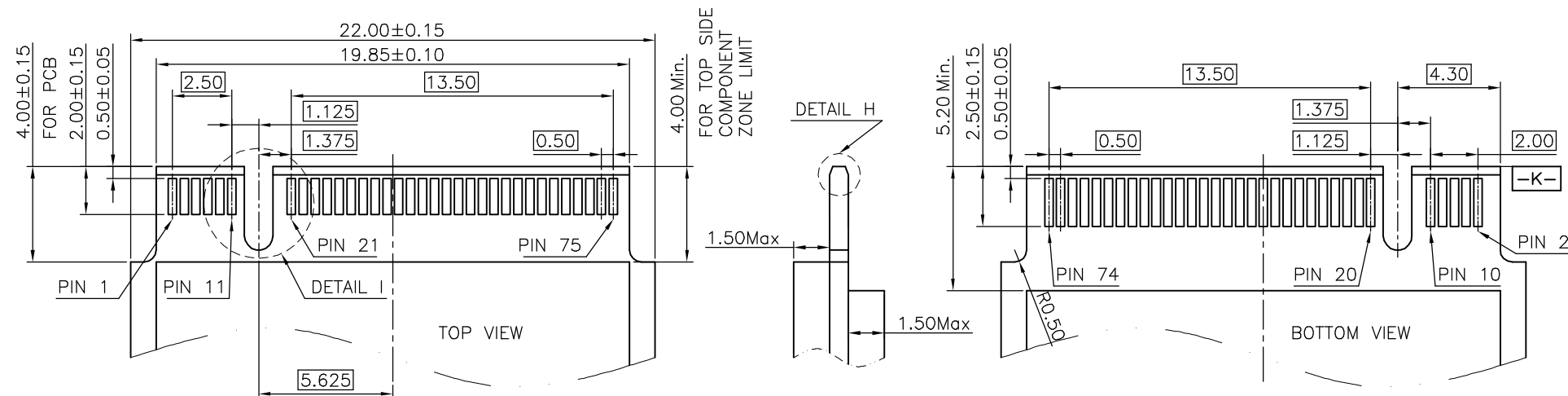
EXTRACT: ⑤ → ⑥

NOTE: Mating force will generate from step 3 to step 4.



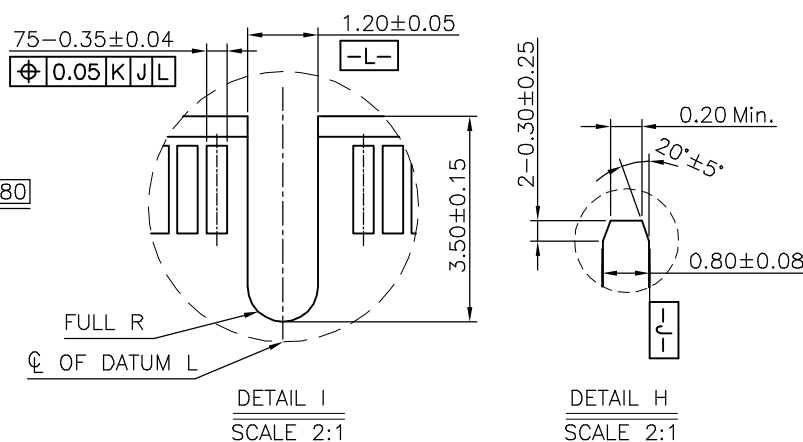
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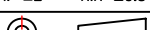
TOLERANCE: X.X ±0.30 X.XX ±0.25 X.XXX ±0.15 X' ±2° X.X' ±0.5°	DRAWN BY : 陈一鸣	DATE : 2014-02-23	PART NAME: NGFF M.2 B KEY 6.7H 0.5PH PCIe 4.0
	CHECKED BY: 马跃	DATE : 2014-02-23	PART NO. HYCW33B-05NGFF-670B
UNIT: mm [inch] SCALE:1:1 SIZE: A4	APPROVED BY: 邱敏	DATE : 2014-02-23	DRAW NO: HYC-2202281723
			SHEET NO. 1 OF 1

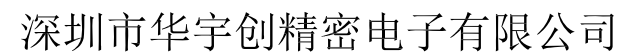


RECOMMENDED PCB LAYOUT(TOP VIEW)

DEFAULT TOLERANCE $\pm 0.05\text{MM}$



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TOLERANCE: X.X ± 0.30 X.XX ± 0.25 X.XXX ± 0.15 X* $\pm 2^{\circ}$ X.X* $\pm 0.5^{\circ}$		DRAWN BY : DATE : 陈一鸣 2014-02-23	
 UNIT: mm [inch]		CHECKED BY: DATE : 马跃 2014-02-23	
		PART NAME: NGFF M.2 B KEY 6.7H 0.5PH PCIe 4.0	
SCALE: 1:1 SIZE: A4 邱敏		PART NO. HYCW33B-05NGFF-670B	
		MOLD NO. 	
		APPROVED BY: DATE : 邱敏 2014-02-23	
		DRAW NO: HYC-2202281723	
		SHEET NO. 1 OF 1	

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